CC112X/CC1200 On-Chip Temperature Sensor

by Bjarte Nystøyl

Keywords

- *Temperature sensor*
- *Calibration*
- *Register settings*
- *CC1120*
- *CC1121*
- *CC1125*
- *CC1200*
- *GBIAS*
- *GPIO*
- *ATEST*

1 Introduction

This design note provides the necessary information in order to use the temperature sensor of the CC112X and CC1200 family. The temperature sensor is based on a Proportional to Absolute Temperature (PTAT) current from a bandgap cell fed to a resistor to generate a PTAT voltage.

Table of Contents

2 Abbreviations

VDD	Supply Voltage
PTAT	Proportional to Absolute Temperature
GPIO	General Purpose Input/Output

3 Operation

The temperature sensor is activated using the register settings of Table 1, which makes the GBIAS output a single-ended voltage measurement on GPIO1.

Register	Value
IOCFG1	0x80
ATEST	0x2A
ATEST_MODE	0x0C
GBIAS1	0x07

Table 1. Register Settings for Temperature Sensor

Setting IOCFG1 to 0x80 configures the GPIO1 pad into analog mode (digital GPIO input and output is disabled). The remaining registers set up the ATEST (analog test) module to output the temperature value as a PTAT voltage on the GPIO1.

4 Temperature Sensor Parameters

General Information	Value	Unit
Temperature sensor fitted from	-40 to +85	°C
Effect of supply voltage deviance	1.17	mV/ VDD-V
Effect of supply voltage deviance	0.44	°C / VDD-V

Changes in the supply voltage affect the voltage of the GPIO pin, and the supply voltage must be stable in order to get accurate temperature sensor readings.

VDD - 2V

Technical Information	Value	Unit
Typical output voltage @ 0 °C	727.42	mV
Typical output voltage @ 25 °C	793.73	mV
Temperature coefficient (t_c)	2.6598	mV / °C

VDD - 3V

Technical Information	Value	Unit
Typical output voltage @ 0 °C	728.55	mV
Typical output voltage @ 25 °C	794.78	mV
Temperature coefficient (t_c)	2.6733	mV / °C

VDD - 3.6V

Technical Information	Value	Unit
Typical output voltage @ 0 °C	730.62	mV
Typical output voltage @ 25 °C	796.94	mV
Temperature coefficient (t_c)	2.6773	mV / °C

Table 2. Typical Temperature Sensor Parameters

5 Calibration

As seen in Figure 2, the CC112X/CC1200 temperature sensor voltage is highly linear, but for some devices there is an offset in the GPIO1 voltage from the typical (average) value that could potentially give an error of up to ±10^{o}C in the temperature reading. In order to ensure accurate temperature sensor measurements the sensor must therefore be calibrated. There are two simple approaches depending on the required accuracy level; single- and two-point calibration.

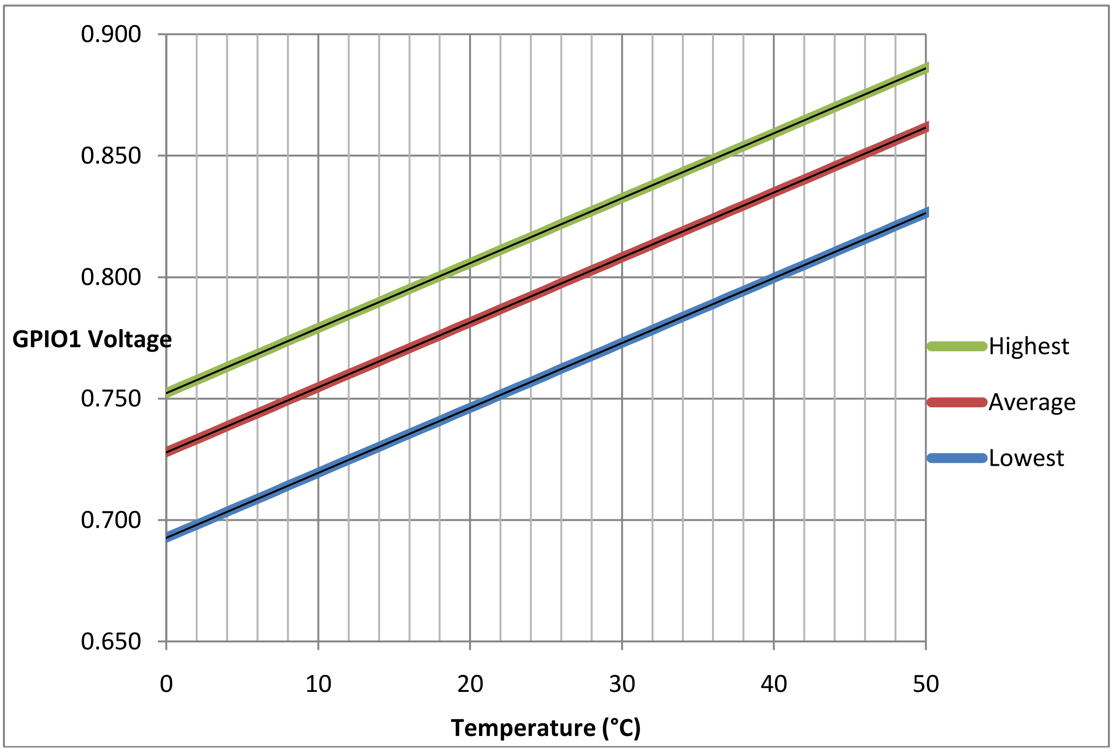

Figure 1. GPIO1 Voltage vs Temperature

5.1 Single-Point Calibration

This is a simple and fast approach, and can be applied for applications targeting approximately ±1^{o}C accuracy within a limited temperature range around the temperature used for the single-point calibration, or approximately ±2^{o}C accuracy across the -40^{o}C to +85^{o}C temperature range.

5.1.1 Performing Single-Point Calibration

The calibration should be performed at the centre of the temperature range in which the device will operate. A given temperature *T* will thus be given as:

$$T = T_{CALIBRATION} + \frac{(V_{MEASURED} - V_{CALIBRATION})}{t_C} \qquad \text{Equation 1}$$

- $T_{CALIBRATION}$ is the temperature when the calibration is performed
- t_c is the temperature coefficient for the given supply voltage (see the typical temperature parameters in Table 2)
- $V_{MEASURED}$ is the voltage of the GPIO1 pin at a given temperature
- $V_{CALIBRATION}$ is the GPIO1 voltage at the calibration temperature

Performing a single-point calibration removes the error caused by the device specific voltage offset seen in Figure 1. The temperature reading accuracy is then limited by the accuracy of the individual temperature coefficients as the *typical* temperature coefficient is used in Equation 1.

Figure 2 shows the maximum error in the temperature reading when using the lowest and highest temperature coefficients out of 30 devices from different processing corners.

- Approximately ±2°C accuracy is possible across the -40°C to +85°C temperature range with single-point calibration and using the *typical* temperature coefficient in Table 2.
- Approximately ±1°C accuracy is possible across the temperature range defined by $T_{CALIBRATION}$ ± 25°C with single-point calibration and using the *typical* temperature coefficient in Table 2.

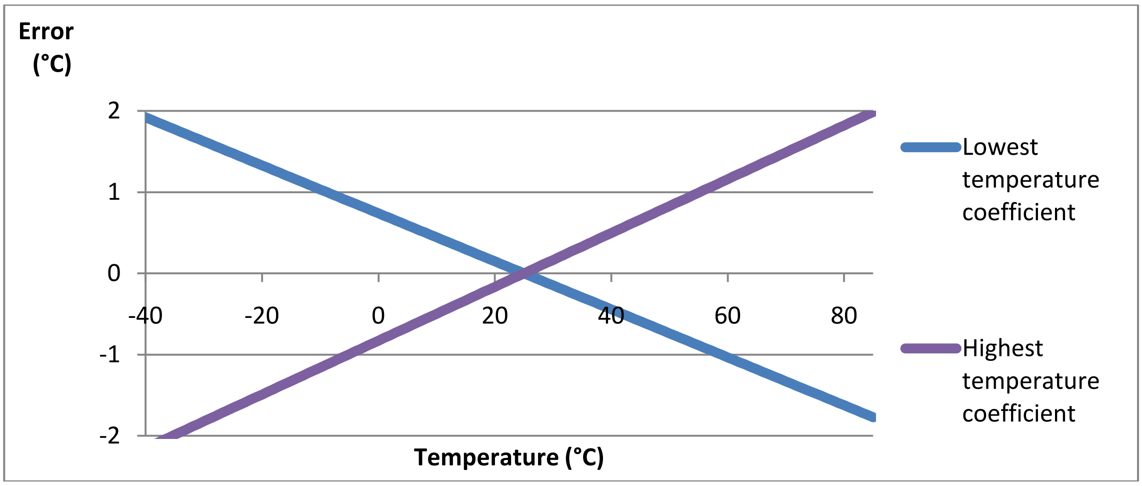

Figure 2. Temperature Error due to Different Temperature Coefficients after Single-Point Calibration

5.1.2 Single-Point Calibration Example

A CC112X/CC1200 device is operated using at 3V supply voltage. The temperature coefficient is typically 2.673 mV/°C and for each degree Celsius increase in temperature the GPIO1 voltage increases by 2.673 mV.

The device is calibrated at room temperature (25°C), and the GPIO1 voltage is measured to be 793.0 mV. After changing the temperature, the GPIO1 voltage is measured to be 830.0 mV. This corresponds to a temperature *T* of:

$$T = 25°C + \frac{(830mV - 793mV)}{2.673mV/°C}$$

$$T = 25°C + 13.84°C = 38.84°C$$

5.2 Two-Point Calibration

If the application requires better accuracy than given by the single-point calibration, a two-point calibration must be used to correct for chip-to-chip variations in the temperature coefficients. As the sensor is highly linear, a two-point calibration will ensure high accuracy across the full temperature range of the chip.

5.2.1 Performing Two-Point Calibration

Choose two calibration temperatures more than 10°C apart, called T_0 and T_1, and set the reference voltage (V_{DD}) to what it will be in the final product (Note that changes in the voltage supply will influence the temperature sensor output). Measure the output from the GPIO1 pin (V_0 and V_1) at the corresponding temperatures.

The temperature coefficient has a *typical* value of 2.673 mV/°C. The *exact* coefficient (t_c) for a given device is calculated as:

$$t_c = \frac{V_1 - V_0}{T_1 - T_0}$$

Using the exact coefficient, the measured voltage of the GPIO1 pin ($V_{MEASURED}$), the temperature (T_0) and the GPIO1 voltage (V_0) of the first calibration, the temperature T can be found as:

$$T = T_0 + \frac{(V_{MEASURED} - V_0)}{t_C}$$

5.2.2 Two-Point Calibration Example

A CC112X/CC1200 device is operated using a 3V supply voltage, and will thus have a typical temperature coefficient of 2.673 mV/°C.

The device is calibrated at two temperatures, 0°C and 25°C (T_0 and T_1). The respective GPIO1 voltages are measured to be 743.379 mV and 808.312 mV (V_0 and V_1). The exact temperature coefficient t_c is thus given as:

$$t_c = \frac{808.312mV - 743.379mV}{25°C - 0°C} = 2.5973mV/°C$$

At a given temperature T, the GPIO1 voltage is measured to be 921.465 mV. This corresponds to:

$$T = 0°C + \frac{(921.465mV - 743.379mV)}{2.5973mV/°C} = 68.57°C$$

Note: Single-point calibration at 25°C, using the typical t_c of 2.673 mV/°C, would in this case give a temperature reading of 67.33 °C, which would have an error of 1.24°C.

5.3 Change in Supply Voltage (VDD)

As seen in Figure 3, the voltage measured on the GPIO1 pin depends on the supply voltage. Changing the supply voltage affects the measured voltage on the GPIO1 pin by typically 1.17 mV/V. This means that if the supply voltage is decreased by 1 V, the voltage measured at the GPIO1-pin is typically 1.17 mV lower.

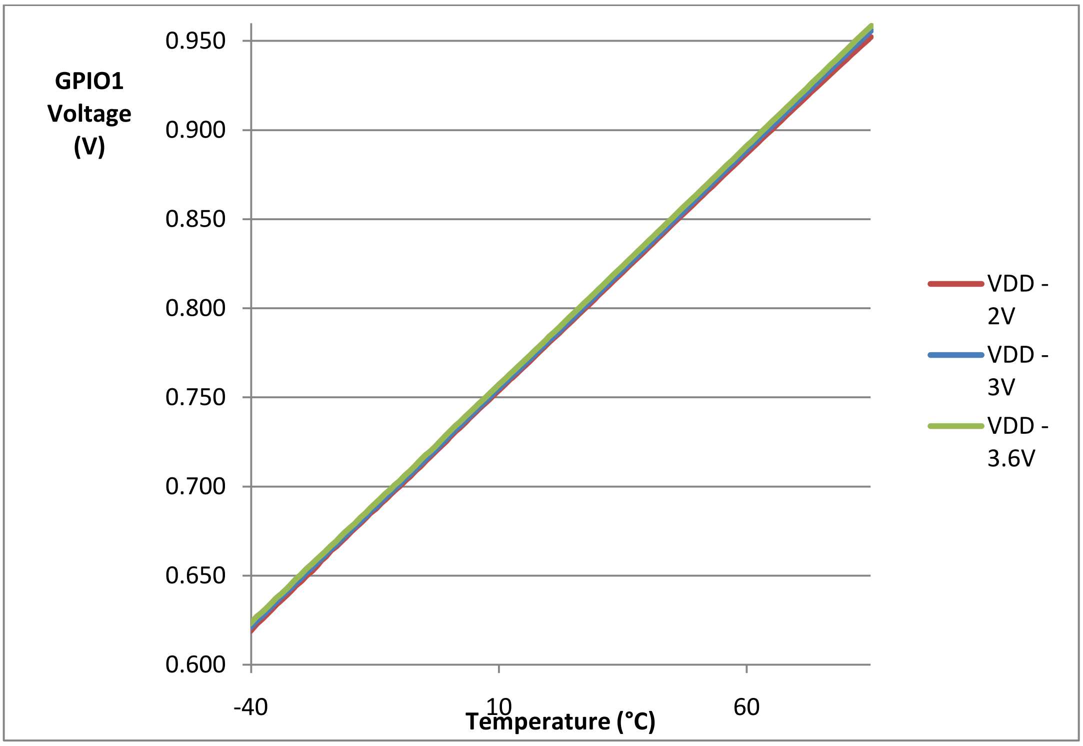

Figure 3. Typical GPIO1 Measurements vs Supply Voltage

6 References

[1] CC1120 Data Sheet (swrs112)

[2] CC1121 Data Sheet (swrs111)

[3] CC1125 Data Sheet (swrs120)

[4] CC112X User Guide (swru295)

7 General Information

7.1 Document History

Revision	Date	Description/Changes
SWRA415	2012.10.30	Initial release.

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